

MAAL-011250-DIE Rev. V2

Features

Noise Figure: 1.4 dB

Gain: 20 dB

· High Input Power Handling

• Including DC Current Regulation

• DC Consumption: 150 mA

Drain Voltage Bias: 8 V

• Input & Output Matched: 50 Ω

• Die Size: 3500 x 1560 x 100 μm

RoHS* Compliant

Applications

Radar

SATCOM

Description

The MAAL-011250-DIE is a very low noise 3 stage LNA designed to operate from 8 to 12 GHz with 1.4 dB of noise figure and 20 dB of gain and is offered in bare die form. It is fully matched across the frequency band.

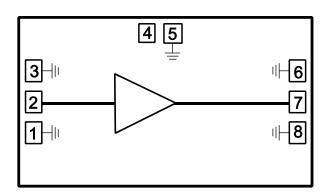
The MAAL-011250-DIE has a single positive and single negative voltage bias which includes a DC current regulation. This LNA is matched to 50 Ω at both input and output ports. This device is ideally suited to satellite communication and radar applications.

The MAAL-011250-DIE is manufactured using a high performance 100 nm gate length GaN on Si HEMT power technology (D01GH). The MMIC uses gold bonding pads and backside metallization and is fully protected with silicon nitride passivation to obtain the highest level of reliability.

Ordering Information

Part Number	Package
MAAL-011250-DIE	DIE
MAAL-011250-SB2	Evaluation Board

Block Diagram



Pad Configuration

Pad #	Function	Function
1,3,5,6,8	GND	Ground
2	RF _{IN}	RF Input
4	V _D	Voltage Drain
7	RF _{OUT}	RF Output

^{*} Restrictions on Hazardous Substances, compliant to current RoHS EU directive.



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Electrical Specifications: Freq. = 8 - 12 GHz, V_D = 8 V, T_A = +25°C

Parameter	Test Conditions	Units	Min.	Тур.	Max.
Noise Figure	_	dB	_	1.4	1.9
Gain	_	dB	17	20	_
OP1dB	_	dBm	_	15	_
Input Return Loss	_	dB	_	11	_
Output Return Loss	_	dB	_	16	_
Current	Total DC current included DC current regulation	mA	_	150	300

Recommended Operating Conditions

Parameter	Unit
Input RF ports	-20 dBm
DC Supply V _D	8 V

Handling Procedures

Please observe the following precautions to avoid damage:

Static Sensitivity

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.

Absolute Maximum Ratings^{1,2,3,4}

Parameter	Absolute Maximum		
Input RF ports	30 dBm		
DC Voltage Drain Supply	12 V		
Junction Temperature7,8	+200°C		
Operating Temperature	-40°C to +85°C		
Storage Temperature	-40°C to +150°C		

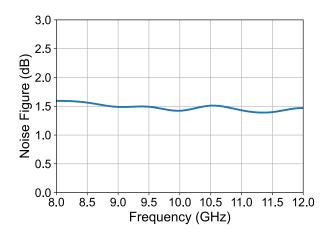
- 1. Exceeding any one or combination of these limits may cause permanent damage to this device.
- MACOM does not recommend sustained operation near these survivability limits.
- 3. Operating at nominal conditions with $T_J \le +150$ °C will ensure MTTF > 1 x 10^{11} hours.
- 4. Junction Temperature (T_J) = T_C + Θ jc * (V * I) Typical thermal resistance (Θ jc) = 32.5° C/W. a) For T_C = $+85^{\circ}$ C, T_J = 125° C @ 8 V, 150 mA



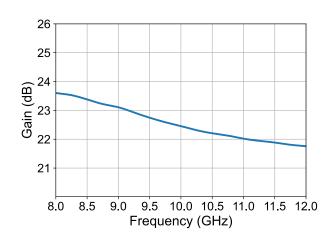
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Typical Performance Curves @ $T_c = 25$ °C in wafer: S-Parameters with 0.1 nH assumed Wirebond

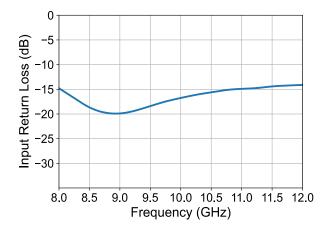
Noise Figure over Frequency



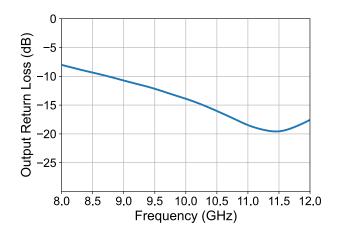
Gain over Frequency



Input Return Loss over Frequency



Output Return Loss over Frequency

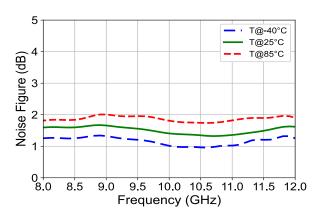




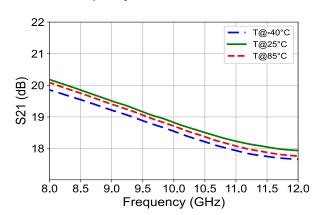
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Typical Performance Curves In board @ $T_c = 25^{\circ}$ C with De-Embedding at different temperature: S-Parameters in CW @ PCB level with De-Embedding

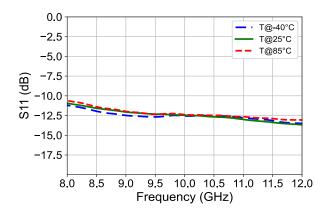
Noise Figure over Frequency



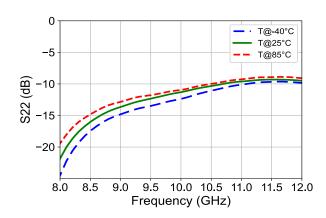
Gain over Frequency



Input Return Loss over Frequency



Output Return Loss over Frequency

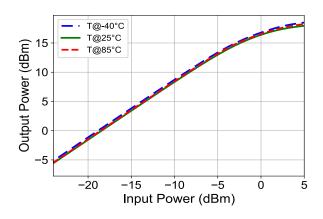




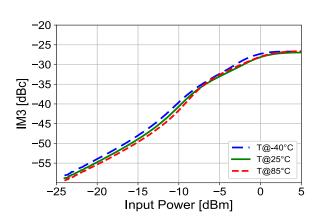
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Typical Performance Curves In Board @ T_c = 25°C with De-Embedding at different temperature

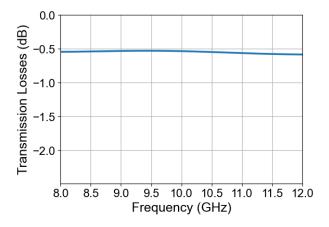
Output power over Input power



IM3 over Input power



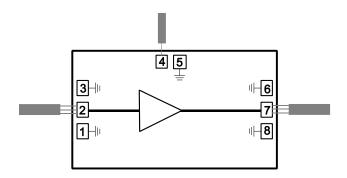
RF access line & connector Losses over Frequency



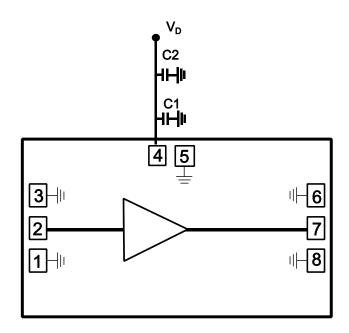


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Recommended Bonding Diagram



Functional Schematic



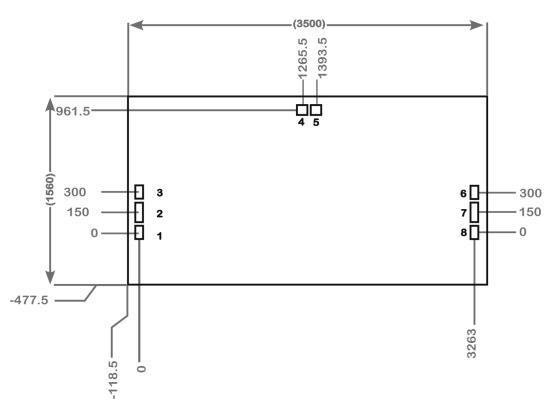
Parts List

Part	Value	Case Style	Manufacturer	Туре	Manufacturer's Part #
C1	47 pF	0.381 mm	KYOCERA AVX	single layer capacitor	116RG470M100TT
C2	10 nF	1005 mm	KYOCERA AVX	SMD multi layer capacitor	0402YC103KAT2A



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Die Outline



PADs Dimensions (µm)

Pad #	X	Y
1,3,6,8	72	97
2,7	72	147
4,5	97	77

Revision History

Rev	Date	Change description
V1	12/29/23	PTRR
V2	12/03/24	Production Release



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